

## AA3527ASESK-50MAV

## 3.5 x 2.7 mm Surface Mount LED Lamp



## DESCRIPTIONS

- The Super Bright Orange device is made with AlGaInP (on GaAs substrate) light emitting diode chip
- · Electrostatic discharge and power surge could damage the LEDs
- · It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

## **FEATURES**

- Single color
- Suitable for all SMD assembly and solder process
- · Available on tape and reel
- Ideal for backlighting
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- RoHS compliant

## **APPLICATIONS**

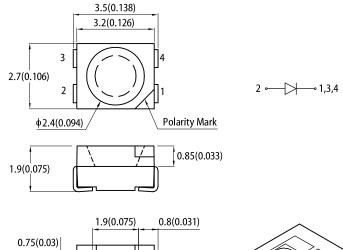
- Backlight
- · Status indicator
- · Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

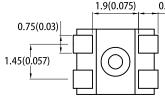
## **ATTENTION**

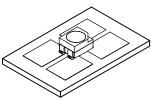
Observe precautions for handling electrostatic discharge sensitive devices



## PACKAGE DIMENSIONS

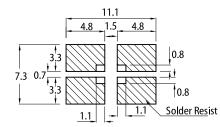






#### **RECOMMENDED SOLDERING PATTERN**

(units : mm; tolerance :  $\pm 0.1$ )



Notes

1. All dimensions are in millimeters (inches).

Tolerance is ±0.25(0.01") unless otherwise noted.
 The specifications, characteristics and technical data described in the datasheet are subject to

change without prior notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.

## **SELECTION GUIDE**

Part Number	Emitting Color (Material)	Lens Type	lv (mcd) @ 50mA <sup>[2]</sup>		Viewing Angle <sup>[1]</sup>	
			Min.	Тур.	201/2	
AA3527ASESK-50MAV	Super Bright Orange (AlGaInP)	Water Clear	400	900	400 <sup>°</sup>	
			*200	*400	120°	

Notes

1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity / luminous flux: +/-15%.
 \* Luminous intensity value is traceable to CIE127-2007 standards.

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### ELECTRICAL / OPTICAL CHARACTERISTICS at T<sub>A</sub>=25°C

Parameter	Current el	Emitting Color	Value		1114
Parameter	Symbol	Emitting Color	Тур.	Max.	Unit
Wavelength at Peak Emission $I_F = 50 \text{mA}$	$\lambda_{peak}$	Super Bright Orange	610	-	nm
Dominant Wavelength I <sub>F</sub> = 50mA	$\lambda_{dom}$ <sup>[1]</sup>	Super Bright Orange	605	-	nm
Spectral Bandwidth at 50% $\Phi$ REL MAX $I_{\rm F}$ = 50mA	Δλ	Super Bright Orange	29	-	nm
Capacitance	С	Super Bright Orange	15	-	pF
Forward Voltage I <sub>F</sub> = 50mA	V <sub>F</sub> <sup>[2]</sup>	Super Bright Orange	2.25	2.6	V
Reverse Current (V <sub>R</sub> = 5V)	I <sub>R</sub>	Super Bright Orange	-	10	uA
Temperature Coefficient of $\lambda_{\text{peak}}$ $I_F$ = 50mA, -10° C $\leq T \leq 85^\circ C$	TC <sub>λpeak</sub>	Super Bright Orange	0.13	-	nm/°C
Temperature Coefficient of $\lambda_{dom}$ $I_F$ = 50mA, -10°C $\leq T \leq 85^\circ C$	TC <sub>λdom</sub>	Super Bright Orange	0.06	-	nm/°C
Temperature Coefficient of $~V_F$ $I_F$ = 50mA, -10°C $\leq$ T $\leq$ 85°C	TCv	Super Bright Orange	-1.9	-	mV/°C

Notes:

The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd : ±1nm.)
 Forward voltage: ±0.1V.
 Wavelength value is traceable to CIE127-2007 standards.
 Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

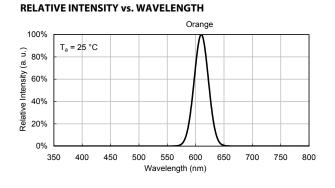
## ABSOLUTE MAXIMUM RATINGS at $T_A = 25^{\circ}C$

Parameter	Symbol	Value	Unit
Power Dissipation	P <sub>D</sub>	130	mW
Reverse Voltage	V <sub>R</sub>	5	V
Junction Temperature	Tj	115	°C
Operating Temperature	T <sub>op</sub>	-40 to +85	°C
Storage Temperature	T <sub>stg</sub>	-40 to +85	°C
DC Forward Current	I <sub>F</sub>	50	mA
Peak Forward Current	I <sub>FM</sub> <sup>[1]</sup>	195	mA
Electrostatic Discharge Threshold (HBM)	-	3000	V
Thermal Resistance (Junction / Ambient)	R <sub>th JA</sub> <sup>[2]</sup>	400	°C/W
Thermal Resistance (Junction / Solder point)	R <sub>th JS</sub> <sup>[2]</sup>	310	°C/W

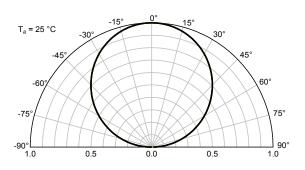
Notes: 1. /1/10 Duty Cycle, 0.1ms Pulse Width. 2. R<sub>in, Ja</sub>, R<sub>in, JS</sub> Results from mounting on PC board FR4 (pad size ≥ 16 mm<sup>2</sup> per pad). 3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

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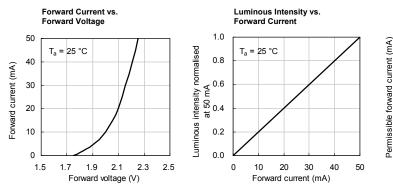
## **TECHNICAL DATA**



#### SPATIAL DISTRIBUTION

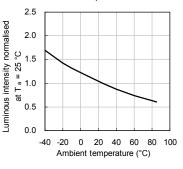


#### **SUPER BRIGHT ORANGE**

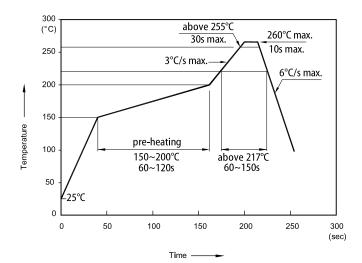


## Forward Current Derating Curve 60 50 40 30 20 10 0 -20 0 20 40 60 80 100 -40 Ambient temperature (°C)

#### Luminous Intensity vs. Ambient Temperature



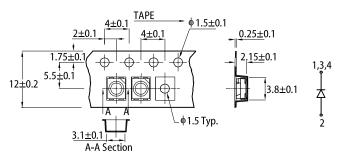
### **REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS**



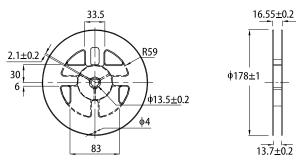
#### Notes.

- Don't cause stress to the LEDs while it is exposed to high temperature.
   The maximum number of reflow soldering passes is 2 times.
   Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

#### TAPE SPECIFICATIONS (units : mm)



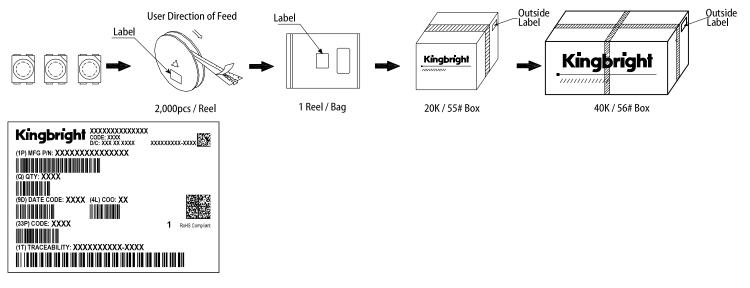
REEL DIMENSION (units : mm)



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## AA3527ASESK-50MAV

### **PACKING & LABEL SPECIFICATIONS**



#### HANDLING PRECAUTIONS

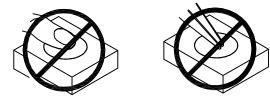
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



precise pickup and avoid damage during production.

2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



 Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



#### **PRECAUTIONARY NOTES**

substances.

5.

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.

4-1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.4-2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.4-3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure

As silicone encapsulation is permeable to gases, some corrosive substances such as H<sub>2</sub>S might corrode silver

plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such

- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to
  the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
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